

NOT RECOMMENDED FOR NEW DESIGN **CONTACT US**



DMG1029SVQ

COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET

Product Summary

Device	BVDSS	R _{DS(ON)} Max	I _D Max T _A = +25°C
04	001/	1.7Ω @ V _{GS} = 10V	500mA
Q1	60V	3Ω @ VGS = 4.5V	400mA
00	001/	4Ω @ VGS = -10V	-360mA
Q2	-60V	6Ω @ V _{GS} = -4.5V	-310mA

Features and Benefits

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Ultra-Small Surface Mount Package
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DIODES™ DMG1029SVQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/quality/product-definitions/

Description and Applications

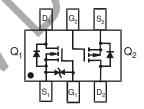
This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP, and is ideal for use in:

- General-purpose interfacing switches
- Power management functions
- Analog switches

Mechanical Data

- Package: SOT563
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See diagram
- Terminals: Finish—Matte Tin Annealed Over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.027 grams (Approximate)





Ordering Information (Note 4)

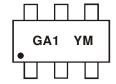
Part Number	Dookowa	Pa	Packing		
Part Number	Package	Qty.	Carrier		
DMG1029SVQ-7	SOT563	3000	Tape & Reel		
DMG1029SVQ-7A	SOT563	3000	Tape & Reel		

1. No purposely added lead, Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. Notes:

Bottom View

- See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information



GA1 = Product Type Marking Code YM = Date Code Marking Y or \overline{Y} = Year (ex: K = 2023) M = Month (ex: 9 = September)

Date Code Key

- are code riej												
Year	2021		2023	2024	2025	2026	2027	2028	2029	2030	2031	2032
Code			K	L	М	N	0	Р	R	S	Т	U
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec



Maximum Ratings N-CHANNEL – Q1 (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage			V _{DSS}	60	V
Gate-Source Voltage	-Source Voltage			±20	٧
Continuous Dunis Comment (Note CVV 10V	Steady State	$T_A = +25$ °C $T_A = +70$ °C	l _D	500 400	mA
Continuous Drain Current (Note 6) V _{GS} = 10V	t < 10s	$T_A = +25$ °C $T_A = +70$ °C	l _D	620 480	mA
Maximum Body Diode Forward Current (Note 6)			ls	500	mA
Pulsed Drain Current (Note 6)			I _{DM}	1000	mA
Pulsed Source Current (Note 6)			Ism	1000	mA

Maximum Ratings P-CHANNEL - Q2 (@TA = +25°C, unless otherwise specified.)

Characteristic				Symbol	Value	Unit
Drain-Source Voltage				V _{DSS}	-60	V
Gate-Source Voltage			\	V _{GSS}	±20	V
Continuous Durin Courset (Nata C) V	Steady State	T _A = +25°C T _A = +70°C		lo	-360 -280	mA
Continuous Drain Current (Note 6) V _{GS} = -10V	t < 10s	$T_A = +25$ °C $T_A = +70$ °C	1	lo	-410 -320	mA
Maximum Body Diode Forward Current (Note 6)				ls	-360	mA
Pulsed Drain Current (Note 6)		1/1/		Ірм	-650	mA
Pulsed Source Current (Note 6)				Ism	-650	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Total Power Dissipation (Note 5)	T _A = +25°C		0.45	W	
Total Fower Dissipation (Note 3)	$T_A = +70$ °C	P _D	0.28	VV	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	D	281	°C/W	
Thermal nesistance, sunction to Ambient (Note 3)	t < 10s	Reja	210	G/ VV	
Total Power Dissipation (Note 6)	T _A = +25°C	Do	1	w	
Total Fower Dissipation (Note o)	T _A = +70°C	P _D	0.62	VV	
Thormal Posistance, Junction to Ambient (Note 6)	Steady State	р	129	°C/W	
Thermal Resistance, Junction to Ambient (Note 6) t < 10s		$R_{ hetaJA}$	97	G/ VV	
Operating and Storage Temperature Range	·	TJ, TSTG	-55 to +150	°C	

5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.



Electrical Characteristics N-CHANNEL – Q1 (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)		•	•			
Drain-Source Breakdown Voltage	BV _{DSS}	60	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current @Tc = +25°C	IDSS	_	_	10	nA	V _{DS} =50V, V _{GS} = 0V
Gate-Source Leakage	Igss	_	_	±50	nA	$V_{GS} = \pm 5V$, $V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	1.0	_	2.5	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$
Static Drain-Source On-Resistance	D	_	1.3	1.7	Ω	$V_{GS} = 10V, I_D = 500mA$
Static Drain-Source On-nesistance	RDS(ON)		1.5	3	12	$V_{GS} = 4.5V, I_D = 200mA$
Forward Transfer Admittance	Y _{FS}	80	_	_	mS	$V_{DS} = 10V, I_{D} = 200mA$
Diode Forward Voltage	VsD	_	_	1.4	V	V _{GS} = 0V, I _S = 115mA
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	Ciss	_	30	-	pF	
Output Capacitance	Coss	_	4.2	-	pF	$V_{DS} = 25V, V_{GS} = 0V,$ f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	2.9		pF	1 - 1.000112
Total Gate Charge	Qg	_	0.3		nC	
Gate-Source Charge	Qgs	_	0.2		nC	$V_{GS} = 4.5V, V_{DS} = 10V,$ $I_{D} = 250mA$
Gate-Drain Charge	Qgd		0.08	_	nC	1D = 25011A
Turn-On Delay Time	td(ON)		3.9	_	ns	
Turn-On Rise Time	t _R	4-7	3.4	7	ns	V _{DD} = 30V, V _{GS} = 10V,
Turn-Off Delay Time	t _{D(OFF)}	17.	15.7	/- ^	ns	$R_G = 25\Omega, I_D = 200 \text{mA}$
Turn-Off Fall Time	t₽		9.9		ns	

Electrical Characteristics P-CHANNEL - Q2 (@TA = +25°C, unless otherwise specified.)

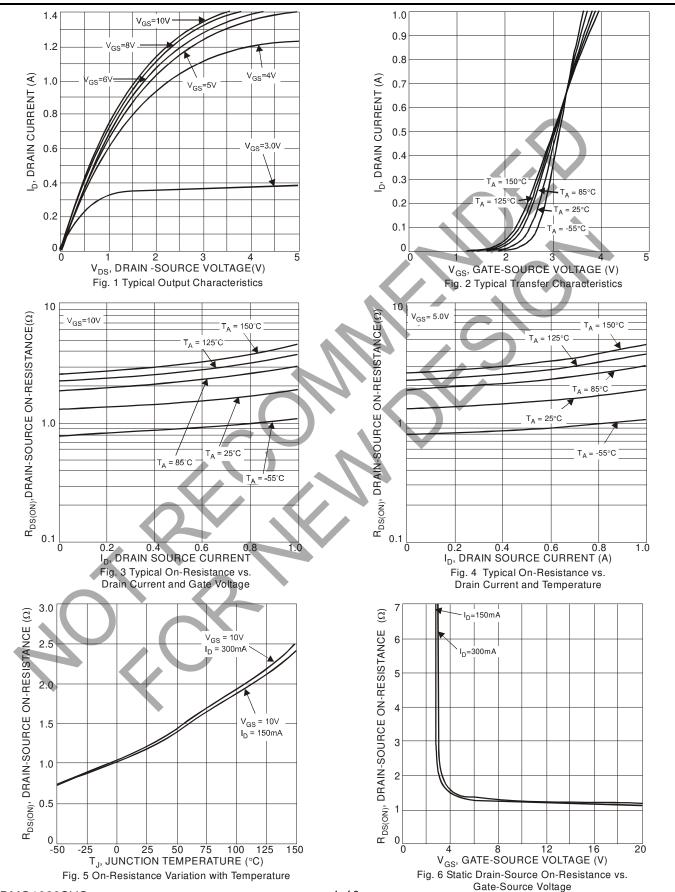
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BVpss	-60	_	_	V	$V_{GS} = 0V, I_{D} = -250\mu A$
Zero Gate Voltage Drain Current @Tc = +25°C	loss	K		-25	nA	V _{DS} = -50V, V _{GS} = 0V
Gate-Source Leakage	Igss			±100	nA	$V_{GS} = \pm 5V$, $V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	-1		-3.0	V	$V_{DS}=V_{GS},I_D=-250\mu A$
Static Drain-Source On-Resistance	Descent		2.7	4	Ω	$V_{GS} = -10V, I_{D} = -500mA$
Static Dialii-Source Off-nesistance	RDS(ON)		3.2	6	12	$V_{GS} = -4.5V, I_D = -200mA$
Forward Transfer Admittance	Y _{FS}	50	1	_	mS	$V_{DS} = -25V, I_D = -100mA$
Diode Forward Voltage	V _{SD}	_	_	-1.4	V	$V_{GS} = 0V, I_{S} = -115mA$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	Ciss	1	25	_	pF	V 05V V 0V
Output Capacitance	Coss	1	4.7	_	pF	$V_{DS} = -25V, V_{GS} = 0V,$ f = 1.0MHz
Reverse Transfer Capacitance	Crss	1	2.7	_	pF	1 - 1.0001112
Total Gate Charge	Qg		0.28	_	nC	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \
Gate-Source Charge	Qgs		0.14	_	nC	$V_{GS} = -4.5V$, $V_{DS} = -10V$, $I_{D} = -500$ mA
Gate-Drain Charge	Qgd	_	0.08	_	nC	- ID = -300IIIA
Turn-On Delay Time	tD(ON)	_	5.5	_	ns	
Turn-On Rise Time	tR	_	7.9	_	ns	V _{DD} = -30V, V _{GS} = -10V,
Turn-Off Delay Time	tD(OFF)	_	10.6	_	ns	$R_G = 50\Omega$, $I_D = -270$ mA
Turn-Off Fall Time	t _F	_	11.6		ns	

Notes: 7. Short duration pulse test used to minimize self-heating effect.

^{8.} Guaranteed by design. Not subject to product testing.

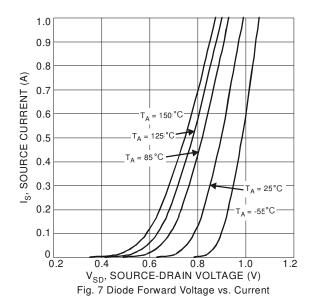


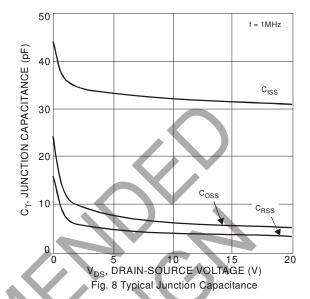
N-CHANNEL - Q1





N-CHANNEL - Q1 (continued)







P-CHANNEL - Q2

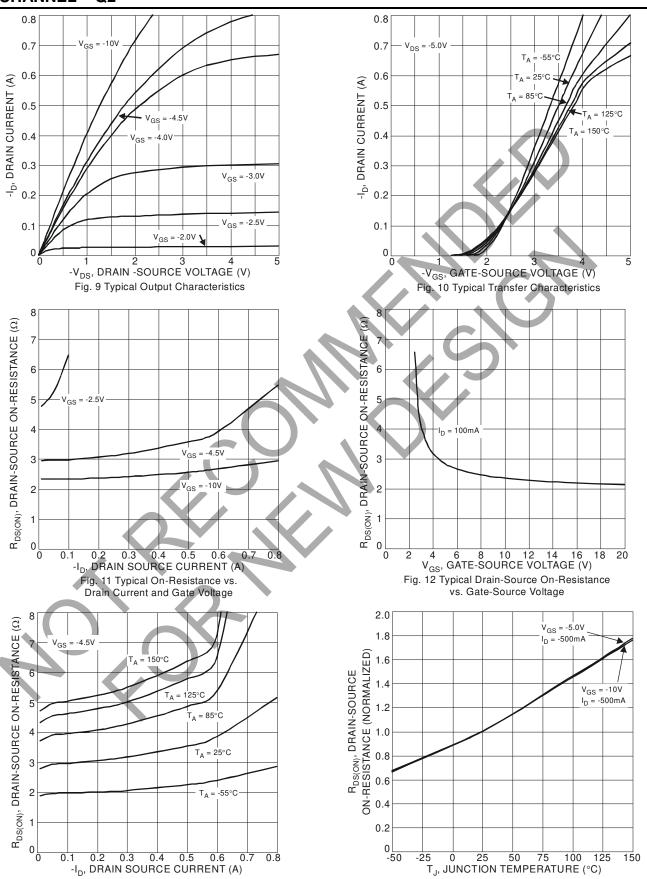
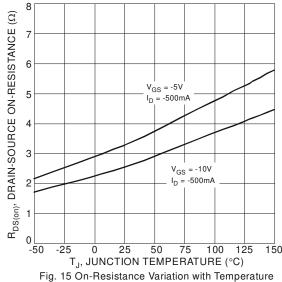


Fig. 13 Typical On-Resistance vs.

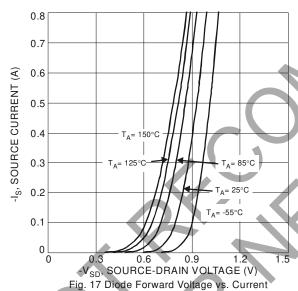
Fig. 14 On-Resistance Variation with Temperature



P-CHANNEL - Q2 (continued)



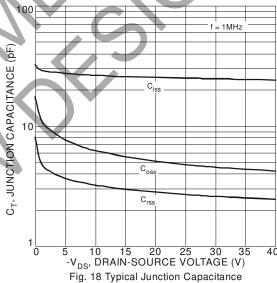




10 $V_{DS} = -10V$ $I_D = -500 \text{mA}$ -V_{GS}, GATE-SOURCE VOLTAGE (V) 0 0.2 0.3 0.4 0.5 0.6 Q_g, TOTAL GATE CHARGE (nC)

Fig. 19 Gate-Charge Characteristics

2.0 $V_{\text{GS(TH)}}$, GATE THRESHOLD VOLTAGE (V) 1.8 1.6 1.4 1.2 1.0 50 -25 0 25 50 75 100 125 150 T_A, AMBIENT TEMPERATURE (°C)
Fig. 16 Gate Threshold Variation vs. Ambient Temperature





Package Outline Dimensions

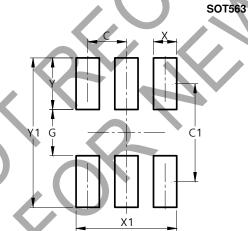
Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT563 E E1 R.01 A A

	SOT563						
Dim	Min	Max	Тур				
Α	0.55	0.60					
b	0.15	0.30	0.20				
C	0.10	0.18	0.11				
D	1.50	1.70	1.60				
E	1.55	1.70	1.60				
E1	1.10	1.25	1.20				
е			0.50				
e1	0.90	1.10	1.00				
L	0.10	0.30	0.20				
а	8°	9°	7°				
All	Dimens	sions in	mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	0.500
C1	1.270
G	0.600
Х	0.300
X1	1.300
Y	0.670
V-1	1 040



IMPORTANT NOTICE

- 1. DIODES INCORPORATED (Diodes) AND ITS SUBSIDIARIES MAKE NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO ANY INFORMATION CONTAINED IN THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).
- 2. The Information contained herein is for informational purpose only and is provided only to illustrate the operation of Diodes' products described herein and application examples. Diodes does not assume any liability arising out of the application or use of this document or any product described herein. This document is intended for skilled and technically trained engineering customers and users who design with Diodes' products. Diodes' products may be used to facilitate safety-related applications; however, in all instances customers and users are responsible for (a) selecting the appropriate Diodes products for their applications, (b) evaluating the suitability of Diodes' products for their intended applications, (c) ensuring their applications, which incorporate Diodes' products, comply the applicable legal and regulatory requirements as well as safety and functional-safety related standards, and (d) ensuring they design with appropriate safeguards (including testing, validation, quality control techniques, redundancy, malfunction prevention, and appropriate treatment for aging degradation) to minimize the risks associated with their applications.
- 3. Diodes assumes no liability for any application-related information, support, assistance or feedback that may be provided by Diodes from time to time. Any customer or user of this document or products described herein will assume all risks and liabilities associated with such use, and will hold Diodes and all companies whose products are represented herein or on Diodes' websites, harmless against all damages and liabilities.
- 4. Products described herein may be covered by one or more United States, international or foreign patents and pending patent applications. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks and trademark applications. Diodes does not convey any license under any of its intellectual property rights or the rights of any third parties (including third parties whose products and services may be described in this document or on Diodes' website) under this document.
- 5. Diodes' products are provided subject to Diodes' Standard Terms and Conditions of Sale (https://www.diodes.com/about/company/terms-and-conditions/terms-and-conditions-of-sales/) or other applicable terms. This document does not alter or expand the applicable warranties provided by Diodes. Diodes does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel.
- 6. Diodes' products and technology may not be used for or incorporated into any products or systems whose manufacture, use or sale is prohibited under any applicable laws and regulations. Should customers or users use Diodes' products in contravention of any applicable laws or regulations, or for any unintended or unauthorized application, customers and users will (a) be solely responsible for any damages, losses or penalties arising in connection therewith or as a result thereof, and (b) indemnify and hold Diodes and its representatives and agents harmless against any and all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim relating to any noncompliance with the applicable laws and regulations, as well as any unintended or unauthorized application.
- 7. While efforts have been made to ensure the information contained in this document is accurate, complete and current, it may contain technical inaccuracies, omissions and typographical errors. Diodes does not warrant that information contained in this document is error-free and Diodes is under no obligation to update or otherwise correct this information. Notwithstanding the foregoing, Diodes reserves the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes.
- 8. Any unauthorized copying, modification, distribution, transmission, display or other use of this document (or any portion hereof) is prohibited. Diodes assumes no responsibility for any losses incurred by the customers or users or any third parties arising from any such unauthorized use.
- 9. This Notice may be periodically updated with the most recent version available at https://www.diodes.com/about/company/terms-and-conditions/important-notice

The Diodes logo is a registered trademark of Diodes Incorporated in the United States and other countries. DIODES is a trademark of Diodes Incorporated in the United States and other countries.

All other trademarks are the property of their respective owners.

© 2023 Diodes Incorporated. All Rights Reserved.

www.diodes.com